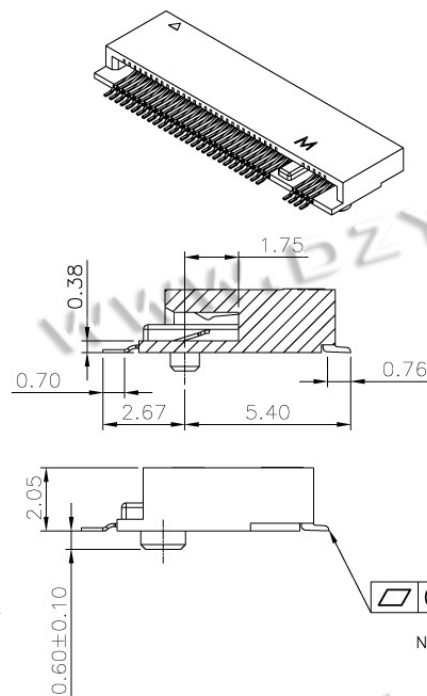
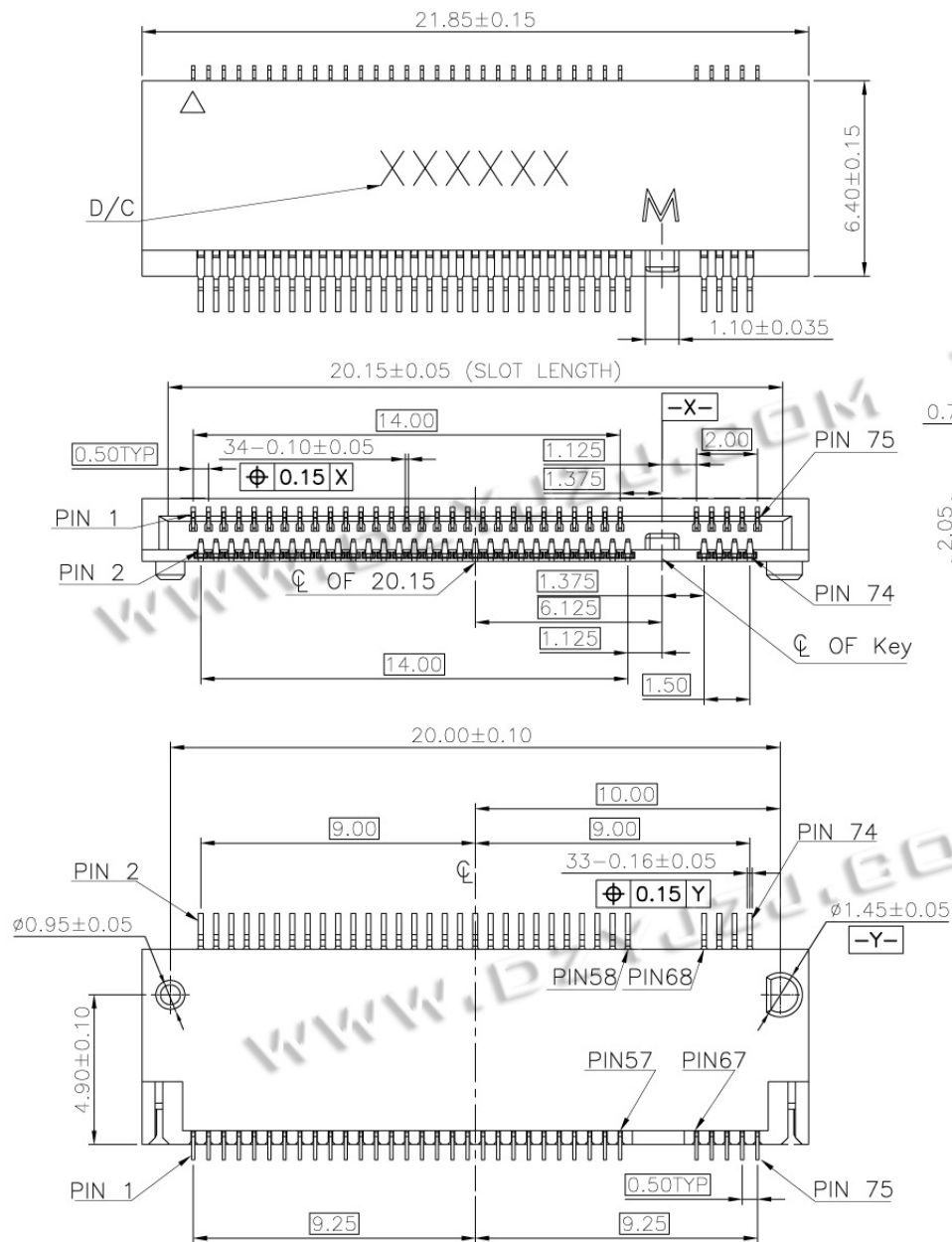




NOTES:

- MATERIAL SPECIFICATION:
1-1. HOUSING: LCP+40%GF, UL94V-0, COLOR: BLACK.
1-2. CONTACT: COPPER ALLOY C1065.
- PLATING SPECIFICATION:
2-1. CONTACT: 50u" MIN. NICKEL UNDER PLATING OVER ALL.
GOLD PLATING ON CONTACT SEE TABLE 1, AND SOLDER AREA IS TIN.
- HF COMPLIANT, ROHS COMPLIANT.
- DATE CODE: XXXXXX
DAY
WEEK
YEAR
- MECHANICAL PERFORMANCE:
5-1. DURABILITY: SEE TABLE
- ELECTRICAL PERFORMANCE:
6-1. CURRENT: 0.5A PER PIN.
6-2. LLCR: INITIAL 55mΩ MAX.; FINAL ΔLLCR=20mΩ MAX..
- IR REFLOW:
THE TEMPERATURE SHALL BE 260±5°C MAINTAINING 10±1 SECONDS.



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TOLERANCE:

x.x ±0.30
x.xx ±0.25
x.xxx ±0.15
x' ±2" x.x' ±0.5"



UNIT: mm [inch]

SCALE: 1:1

SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

NGFF M.2 M KEY 2.3H 0.5PH

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYC25M-05NGFF-230

MOLD NO.

APPROVED BY:

邱敏

DATE :

2014-02-23

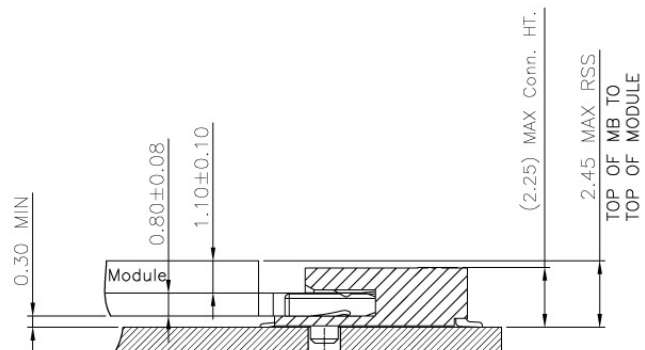
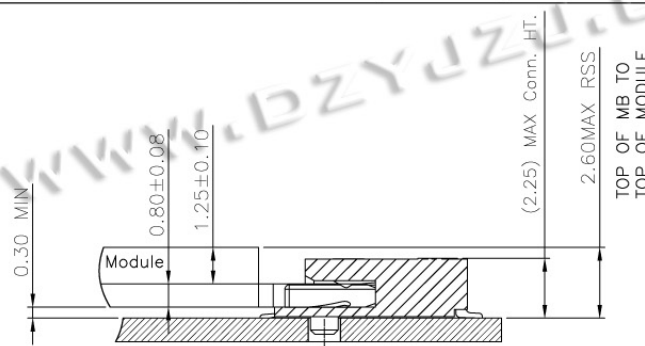
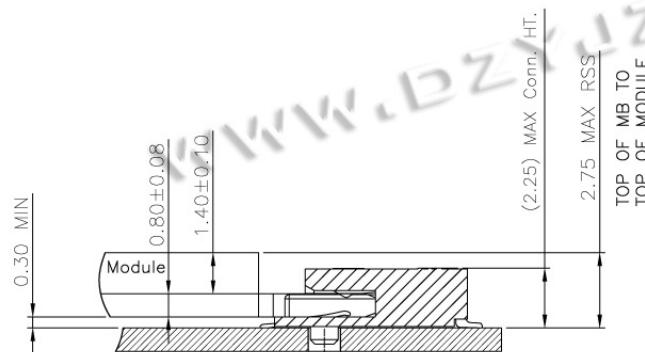
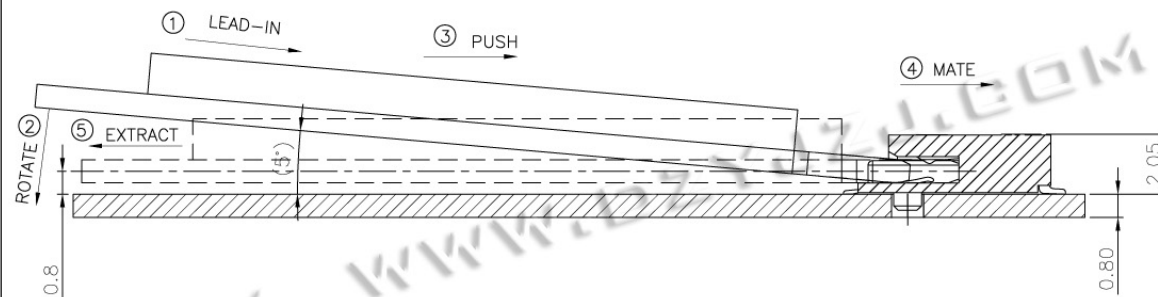
DRAW NO:

HYC-2205061831

SHEET NO.

1 OF 1

Assembly stack height schematic diagram

Stack-up Top Mount Single Sided Module
for 1.20 max top-side component heightStack-up Top Mount Single Sided Module
for 1.35 max top-side component heightStack-up Top Mount Single Sided Module
for 1.5 max top-side component height

HOW TO MATE AND EXTRACT

MATE: ① → ④

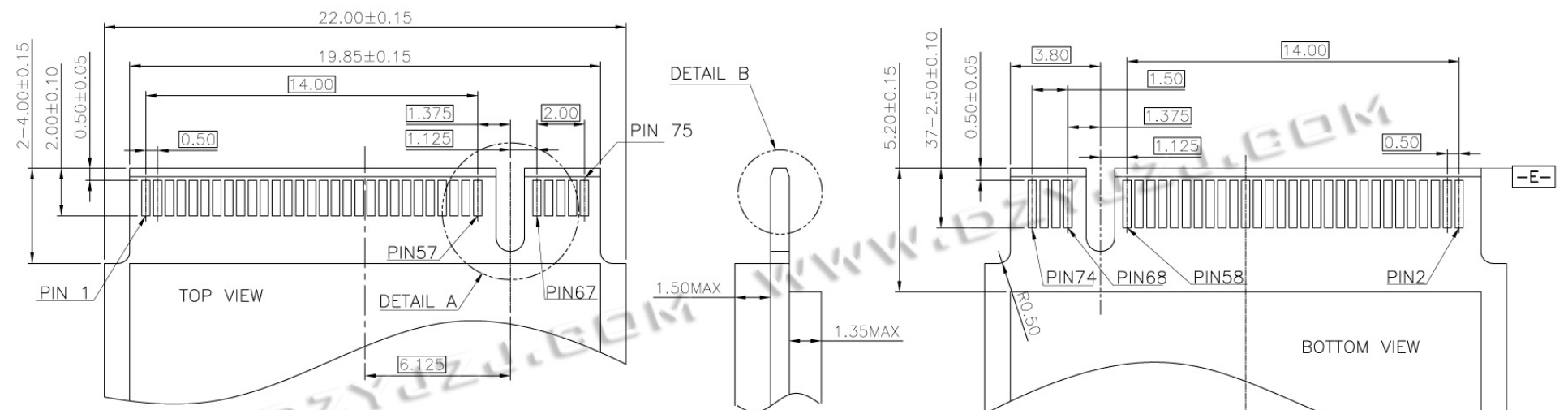
EXTRACT: ⑤

NOTE: Mating force will generate from step 3 to step 4.



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: NGFF M. 2 M KEY 2.3H 0.5PH
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC25M-05NGFF-230
	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.
	SCALE:1:1 SIZE: A4		DRAW NO: HYC-2205061831
			SHEET NO. 1 OF 1



RECOMMENDED PCB LAYOUT(TOP VIEW)
DEFAULT TOLERANCE ±0.05MM



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: NGFF M.2 M KEY 2.3H 0.5PH
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC25M-05NGFF-230
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2205061831
			SHEET NO. 1 OF 1